**Minutes – 250618**

**Present: IT, SW, AG, HH, JT, SB**

**Apologies: PS, PD** (physics co-ordinator meeting), **AG, SW**

**Strip modules**

Thermally cycle 3 modules… -90 to +120. Still worked !

1 continues over weekend.

Hybrids will not be cold tested : too risky for corrosion to do all. Biggest risk during assembly stage

Prepare documents for September.

Production meeting – before ITk week.

Priority: wrap up tooling. Build 2 electrical modules. Have sensors from Bart.

LS module being readout.

**Have drawings for 1st tool. => to give to workshop. Other parts will follow on by end of this week. More jigs needed for production. Can come later.**

**Invitation to ITk week.**

QA/QC meeting next week in oxford. Mon-thurs. Cold test on Friday. QA on some hybrids. Maybe just Sw or AG for the Friday. Accommodation v. expensive.

AG: brookhaven module works. Priority is for test frame . CMS DCDC problem fixed.

SW: building hybrds for tests, engineering drawings

**Strip Mechanics**

**Dave/ Tim and Peter to build first stave core.**

Monica dO would like Hamish to start. Try to start next week when PS, TJ, DS are around. One issue: how to grind honeycomb. Custom grinding attachment? Get piece of honeycomb , see how grinding works.

DS: weight is on old CF lab. Setting up environment.

*Stave core tool assembly meeting last week.*

*Oxford are not happy with Jeff’s leadership ?*

*Tim was accidental chair?*

*Aggressive schedule-> design for core frozen this month. Approved end of July.*

*Need to build 13 module stave core -> TJ/DS (after pixelfest).*

**Pixel modules**

JT: adapting IT transport box with silicon modules for testing. The molds take a while to adapt. Take 1 day . needs to adapted further for single chip flexes.

IT : tested hybrids for QC. All but one is good. Issue with connector. Procurement issue.

Gluing modules for Jon. First attempt failed. Used roller to deposit glue.

Open windows in solder resisit.

Give one week to try Kapton micro-hole technique for glue deposit.

Jessica’s module -> get working. Need it back end of this week.

JT sent CF bits to Glasgow.

YG to clarify Yarr firm ware. No working firmware for FEI4 or ,….. talk to Lancaster.

UK: oxford in same position as us.

***JT:***  *meeting with RB, PD, : RD53A modules – single chip crads. 5 or 6 here. Make transport box. Send for irradiation . CFRP mounted chips for irradiation. Pitch adapter. Ready for July testbeam just in case.*

*Other testbeams august/October.*

*Alternative desy/fermilab*

*PS closes.*

*IT: have solded hv wire. Disabled hv from connector. Bring to 800 V ?*

*Playing with new hybrid design. Setup measuemnets of 8 new hybrids. Drop new flex design in eagle. => translate to “aldium” common design tool.*

*Assembly method: give up paper, give up stamp. Use cleanroom doormats. Order blue film. Mask edges, use roller. => qualify it. Followup on silicon mold. Liase with PC to make mold.*

*Cut 10 dummy Kapton dummys. Evaluate roller method. YY to help.*

*YYG making progress with Yarr. Need software to flush. Not develop. IT to help YYG .*

*Probably not set up YArr for FEI4. Problem with fnc card.*

 *Argonne approached IT to help with their hybrid.*

*Alan is hero: UBM done by Leti. Do not use LETI. We have to start from ground up. All bumb bonding needs to be established from scratch . ask IZM. Ask micron to do UBM.*

*Liverpool volunteer to do vibration tests? 10kHz*

***Pixel Mechanics***

*Not much progress in the last week. TJ: re-evaluted cost of half sheets – discuss with CB, JP and TJ, HH this week.*

*HH to look at Pixel EC services.*

*Work shop effort: ask for update from Mark Whitley on workshop and Peter Cooke on ATLAS effort. => standing items on LAU.*

*University cars.*